

Features

1. The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
2. For surface mounted applications
3. Metal silicon junction, majority carrier conduction
4. Low power loss, high efficiency
5. Built-in strain relief, ideal for automated placement
6. High forward surge current capability
7. High temperature soldering guaranteed:
250 °C/10 seconds at terminals

Mechanical Data

Case : JEDEC SOD-123FL molded plastic body

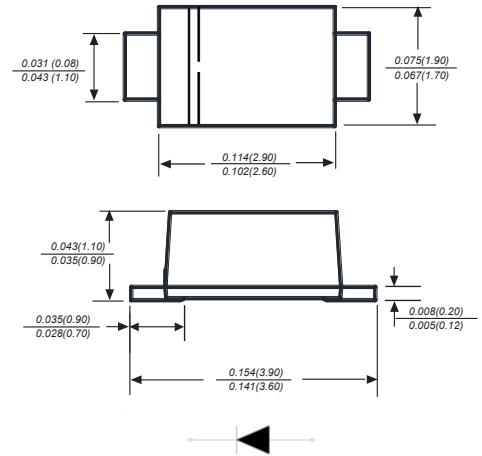
Terminals : Solderable per MIL-STD-750,
Method 2026

Polarity : Color band denotes cathode end Mounting

Position : Any

Weight : 0.0007 ounce, 0.02 grams

SOD-123FL



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave

60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	DSK12	DSK14	DSK15	DSK16	DSK18	DSK110	DSK115	DSK120	UNITS
Marking Code		K12	K14	K15	K16	K18	K110	K115	K120	
Maximum repetitive peak reverse voltage	V _{RRM}	20	40	50	60	80	100	150	200	V
Maximum RMS voltage	V _{RMS}	14	28	35	42	56	70	105	140	V
Maximum DC blocking voltage	V _{DC}	20	40	50	60	80	100	150	200	V
Maximum average forward rectified current at TL(see fig.1)	I _(AV)	1.0								A
Peak forward surge current 8.3ms single half sine-wave superimposed onrated load (JEDEC Method)	I _{FSM}	25								A
Maximum instantaneous forward voltage at 1.0A	V _F	0.55		0.70		0.85			0.95	V
Maximum DCreverse current T _A =25℃ at rated DCblocking voltage T _A =125℃	I _R	0.5					0.1			mA
		10.0			5.0		2.0			
Typical junction capacitance (NOTE 1)	C _J	110		80						pF
Typical thermal resistance (NOTE 2)	R _{θJA}	100.0								℃/W
Operating junction temperature range	T _J	-55 to +125								℃
Storage temperature range	T _{STG}	-55 to +150								℃

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Typical Characteristics

Fig.1 Forward Current Derating Curve

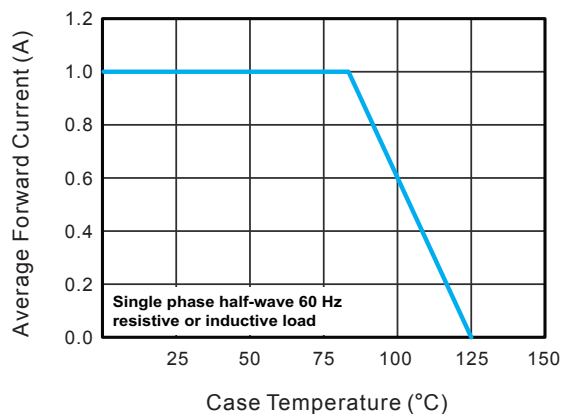


Fig.2 Typical Reverse Characteristics

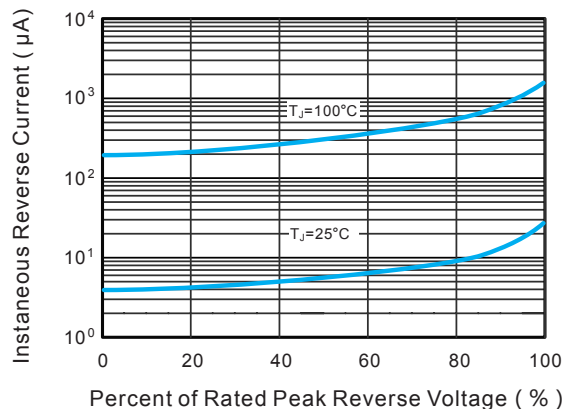


Fig.3 Typical Forward Characteristic

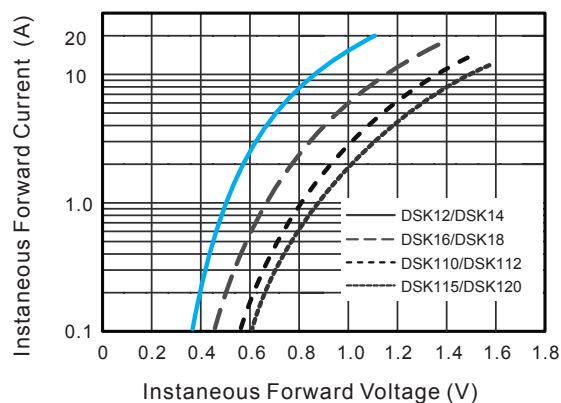


Fig.4 Typical Junction Capacitance

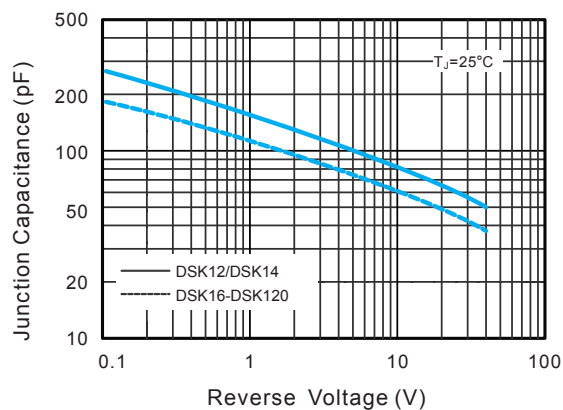


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

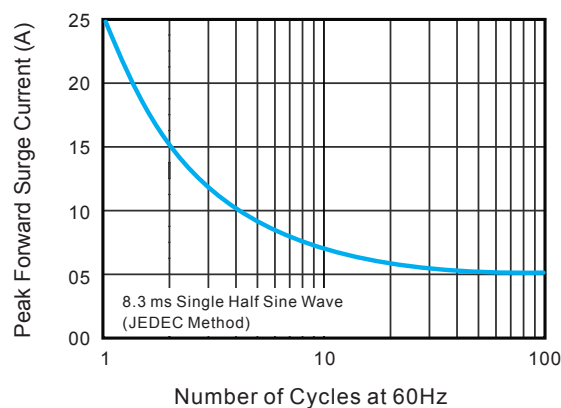
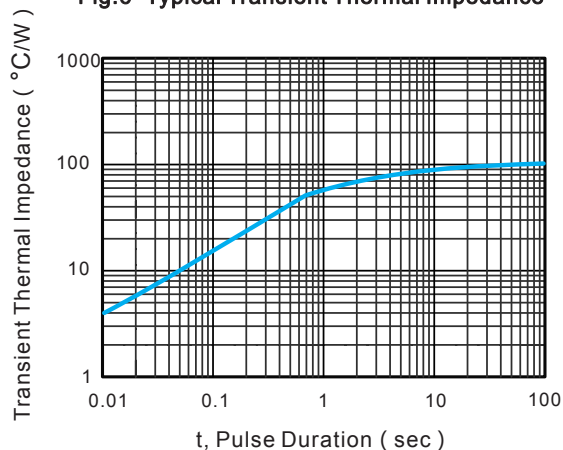
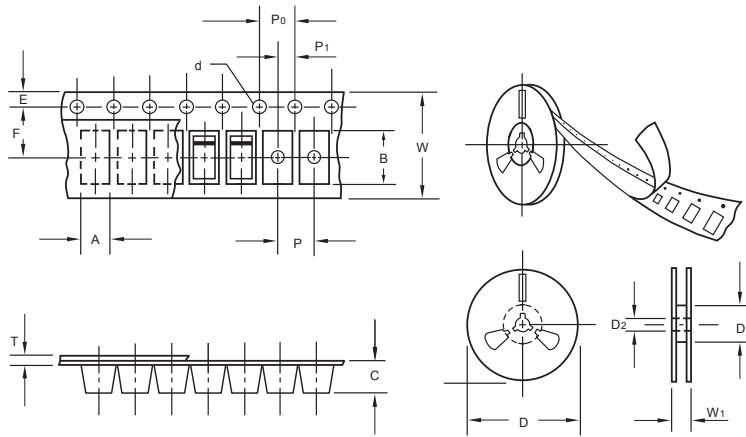


Fig.6- Typical Transient Thermal Impedance



Packing information



unit:mm

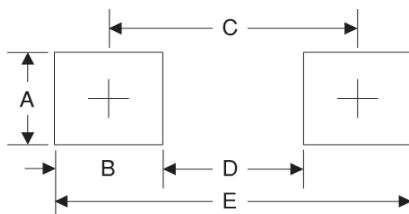
Item	Symbol	Tolerance	SOD-123FL
Carrier width	A	0.1	2.1
Carrier length	B	0.1	4.0
Carrier depth	C	0.1	1.60
Sprocket hole	d	0.05	1.55
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	50.0
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	8.15
Reel width	W ₁	1.0	10.5

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-123FL	7"	3,000	4.0	45,000	210*208*203	178	430*430*235	180,000	9.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.2	0.047
B	1.2	0.047
C	3.2	0.126
D	2	0.079
E	4.4	0.173